

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1484	(216/41).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/17 11:29
S2	34	(216/45).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/17 13:21
S3	10	S2 and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/30 17:42
S4	631	(edge near2 wafer) near3 (solution or liquid or fluid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/17 13:24
S5	57	((edge near2 wafer) near3 (solution or liquid or fluid)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/30 17:44
S6	149	((edge near2 wafer) near3 (solution or liquid or fluid)).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/30 17:44
S7	42	(156/345.19).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/30 17:47
S8	3	(sax near2 harry).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/30 17:50
S9	2	("5896877").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/30 17:50

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S10	7	(edge near2 wafer) near3 (solution or liquid or fluid) and (second adj distance)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/31 13:09
S11	517	(edge with mask\$3 with wafer) and (solution or liquid or fluid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/15 16:33
S12	3	(edge with (second adj distance) with wafer) and (solution or liquid or fluid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/15 16:34
S13	24	(edge with (second adj distance) with (wafer or substrate)) and (solution or liquid or fluid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/15 16:36
S14	519	(edge with (treat\$4) with (wafer or substrate)) with (etchant or solution or liquid or fluid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/15 16:36
S15	128	(edge and (treat\$4 or apply\$4 or etch\$3 or coat\$3) with (wafer or substrate) with (etchant or solution or liquid or fluid)).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/15 16:38
S16	2125	(edge and (treat\$4 or apply\$4 or etch\$3 or coat\$3) with (wafer or substrate) with (etchant or solution or liquid or fluid)).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/15 16:38
S17	1165	(edge and (treat\$4 or apply\$4 or etch\$3 or coat\$3) with (wafer or substrate) with (etchant or solution or liquid or fluid)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/15 16:38
S18	2	("5896877").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/17 13:18
S19	513	(216/92).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/27 10:50

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S20	50	(edge near2 (wafer or substrate or treat\$4)) and S19	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/17 13:58
S21	6	((("6203218") or ("5688411") or ("6550091"))).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/17 13:48
S22	245	438/748	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/17 13:48
S23	13	("5608943" "5706843" "5769945" "5861061" "5871584" "5896877" "5904164" "5945351" "6013136" "6095582" "6140254" "6162739" "6334902").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/11/17 13:55
S24	19	mok.in. and bevel	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/17 13:58
S25	764	((wafer or substrate) and edge and (etch\$3 or treat\$5 or remov\$3)).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/17 15:02
S26	100	((wafer or substrate) and edge and (etch\$3 or treat\$5 or remov\$3)).ti. and second	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/17 15:08
S27	192	((wafer or substrate) and edge and mask\$3).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/17 15:34
S28	189	sez.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/17 15:48
S29	603	(216/88).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/27 10:51

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S30	514	(216/92).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/27 10:51
S31	38	S29 not (CMP or polish\$3 or planariz\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/27 10:52
S32	3	("6805898").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/05/09 11:54